

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: KIM, Sangyum; CHOI, Chang Hee; JO, Cha Jae; KIM, Jeong Ik; WOO, Kyung  
Nyung; KI, Joon Seo; MOON, Hong Gi

SERIAL NO.: 10/720,579 ART UNIT: 1753

FILED: November 24, 2003 EXAMINER: Wong, E.

TITLE: METHOD FOR MANUFACTURING VERY LOW ROUGHNESS  
ELECTRODEPOSITED COPPER FOIL AND ELECTRODEPOSITED COPPER FOIL  
MANUFACTURED THEREBY

RESPONSE "A"

Director of the U.S. Patent  
and Trademark Office  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action of July 9, 2007, a response being due with a shortened  
statutory period for response set to expire on August 9, 2007, please consider the following remarks:

REMARKS

In the Official Action, Restriction was required between the two subject matter of Group I,  
namely Claims 1 - 11 as drawn to a method for manufacturing an electrodeposited copper foil; and  
Group II, namely Claims 12 - 15 as drawn to a low roughness electrodeposited copper foil.

Applicant herein elects the subject matter of Group I, namely Claims 1 - 11. Applicant  
reserves the right to take such appropriate measures as he deems appropriate so as to protect the  
subject matter of the non-elected invention, such as the filing of a divisional application.

Based upon the foregoing analysis, Applicant contends that an Official Action on the merits is in order and such is respectfully requested.

Respectfully submitted,

<u>August 4, 2007</u>	<u>/Andrew W. Chu/</u>
Date	John S. Egbert Reg. No. 30,627 Andrew W. Chu Reg. No. 46,625
Customer No. 24106	Attorney for Applicant Egbert Law Offices 412 Main Street, 7 <sup>th</sup> Floor Houston, Texas 77002 (713)224-8080 (713)223-4873 fax

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CERTIFICATE OF MAILING UNDER 37 CFR 1.8(a)

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

I hereby certify that the attached correspondence comprising:

RESPONSE "A"

is being deposited with the United States Postal Service with sufficient postage as first class mail  
in an envelope addressed to:

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

on August 4, 2007.

Respectfully submitted,

August 4, 2007

/Andrew W. Chu/

Date

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